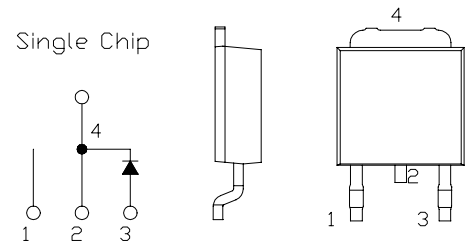


# SBD Type : EA30QS10-F

## OUTLINE DRAWING

### FEATURES

- \* TO-252AA Case, Surface Mounting Device
- \* Low Forward Voltage drop
- \* Low Power Loss
- \* High Surge Capability
- \* 40 Volts thru 100 Volts Types Available
- \* Packaged in 16mm Tape and Reel



### Maximum Ratings

Approx Net Weight:0.30g

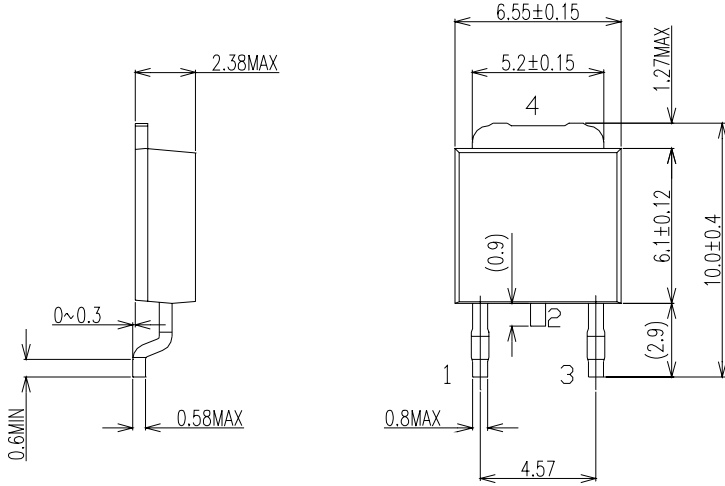
Rating		Symbol	EA30QS10-F			Unit
Repetitive Peak Reverse Voltage		V <sub>RRM</sub>	100			V
Average Rectified Output Current	P.C.Board mounted *	I <sub>O</sub>	1.6	Ta=34°C	50Hz Half Sine Wave Resistive Load	A
	-		3.0	Tc=133°C		
RMS Forward Current		I <sub>F(RMS)</sub>	4.71			A
Surge Forward Current		I <sub>FSM</sub>	45	50Hz Half Sine Wave,1cycle, Non-repetitive		A
Operating JunctionTemperature Range		T <sub>jw</sub>	- 40 to + 150			°C
Storage Temperature Range		T <sub>stg</sub>	- 40 to + 150			°C

### Electrical • Thermal Characteristics

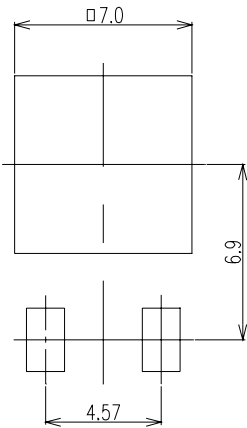
Characteristics		Symbol	Conditions	Min	Typ	Max	Unit
Peak Reverse Current		$I_{RM}$	$T_j=25^{\circ}\text{C}, V_{RM}=V_{RRM}$	-	-	1.0	mA
Peak Forward Voltage		$V_{FM}$	$T_j=25^{\circ}\text{C}, I_{FM}= 3 \text{ A}$	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	P.C.Board mounted *	-	-	80	$^{\circ}\text{C/W}$
	Junction to Case	$R_{th(j-c)}$	-	-	-	6	$^{\circ}\text{C/W}$

\* Print Land = 20x20 mm

## EA30QS10-F OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD



## Single Chip

